

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/809,182 Confirmation No. 6820  
Applicant(s) : UMENO, Kuniharu et al.  
Filed : 03/25/2004  
TC/A.U. : 1712  
Examiner : Robert E. Sellers  
Title : Resin Composition for Encapsulating Semiconductor Chip and  
Semiconductor Device Therewith

Docket No. : 033036.076  
Customer No. : 25461

**MAIL STOP AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

**SUPPLEMENTAL AMENDMENT**

Further in response to the Office Action of June 28, 2006, please amend the above-identified application as follows:

**Amendments to the specification** are reflected beginning on page 2.

**Remarks/Arguments** begin on page 9 of this paper.